

Soldering System

KOKI TEC CORP.

Distribution Agent

Benchtop Selective Soldering Series

- Automated hand soldering
- Space saving & energy saving
- Suitable for many varieties and small lot production
- Light wait & flexible layout
- Achieved low price for easy introducing
- Reduction of the flux amount with selective spraying
- Soldering quality supporting system "D-arwin"
- Easy operation & program creation



In-line Type Selective Soldering Series

- Suitable for automated mass production
- Available for mixed flow production
- Achieved modularization (SELBO II)
- Compatible from 1 to 3 soldering units
- Reduction of tact time with various nozzle selection



Wave Soldering Series

- Excellent spraying efficiency
- Spray fluxer with lesser contamination
- N2 tunnel structure without blocking curtains (N2 wave soldering)
- Compatible with production control system
- Externally-operable peel-back point adjustment system



All-in-one Type Selective Soldering Series

- Capable of larger size PCBs
- Compatible with high-spec and multi-layer PCBs
- Robot arm transportation (ROBO-DIP)
- Upper & lower preheaters (Rashin)
- Equipped with dual nozzles (Rashin)
- Variety of options



Page-9-10 Peripherals

- Dip Tester for selective soldering system
- Small-size PSA



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Benchtop Selective Soldering Series



ULTIMA-SSP ULTIMA-SSP-L

Outer Dimensions	Outer Dimensions
630Wx640Lx365H mm	840Wx800Lx395H mm
PCB Size	PCB Size
50x50 - 250x330 mm	50x50 - 380x460 mm
Machine Weight	Machine Weight
Approx. 45 Kg	Approx. 60 Kg
Power Source	Power Source
AC100-240V	AC100-240V
Air	Air
0.4-0.5mps	0.4-0.5mps
Tank Capacity	Tank Capacity
0.75ℓ	0.75ℓ

ULTIMA-TRZ ULTIMA-STR2-L

Outer Dimensions	Outer Dimensions
620Wx940Lx442H mm	1081Wx1300Lx1025H mm
PCB Size	PCB Size
50x50 - 250x330 mm	50x50 - 380x460 mm
Machine Weight	Machine Weight
Approx. 125 Kg	Approx. 180 Kg
Power Source	Power Source
Single-phase 200V	Single-phase 200V
Air	Air
0.4-0.5mps	0.4-0.5mps
N2	N2
0.4-0.5mps/25ℓ/min 99.99%	0.4-0.5mps/25ℓ/min 99.99%

AOI system D-arwin

Soldering quality supporting system
The soldering device receives inspection results. This is a next generation system with the potential of evolution by inspection data-sharing function. (PATENT PENDING)

Benchtop type preheating unit equipped with far infrared panel.



Improving Productivity

Productivity	Operators	Material
1,300 pcs/day	6 people	18 Kg
1,500 pcs/day	2 people	4 Kg
Increases 15%	Reduces 2/3	Significant reduction

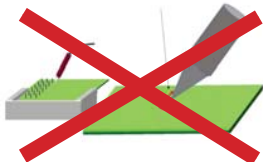
Introduction Benefits

- ① Cost reduction(material)
- ② Labor cost reduction
- ③ Quality improvement & stability
- ④ Space & energy saving

Difficult to secure operators?

Worry about soldering quality?

Here is a solution.



Cost comparison between Ultima-TRZ and conventional wave soldering.

	Electric Energy	Co2 Emission	Finger Cleaner	Oxide Dross	N2 Usage	Capital Investment
Wave Soldering	6.6kw(Ave.)	915kg	125L	100g/h	300L/min	
ULTIMA-TRZ	1.0kw(Ave.)	138kg	-	12.5g/h	25L/min	
Reduction	85% reduction	85% reduction	100% reduction	88% reduction	92% reduction	78% reduction
Palette Cost	100% reduction	Total reduction per month on simulation				
Flux Usage	97% reduction	Selective system 92% reduction				

Reduction example of introduced user

Selective system		
Soldering	270 sec	885 min of time taken by hand soldering ↓ 275 min
PCB change	60 sec	
330 sec × 2 sides × 50 sheets = 275 min		



Soldering quality supporting system "D-arwin"



1. Improve soldering quality

- Soldering system and inspection machine share the data.
- Various soldering inspection items
- Greatly reduces the risk of outflowing defective products to the market.



2. Shorten the time for improvement

- Soldering system automatically and instantly captures inspection results.
- **Highlights a defect part (s)** in the soldering program.
- **Displays suggestion (s)** of improvement.



3. Keep a history of solder quality inspection

- **Inspection results, defect images,** soldering conditions and production history can be stored.

All-in-one Type Selective Soldering Series



IRD-2533 "ROBO-DIP"

Outer Dimensions 1800Wx1500Lx1600Hmm	Flux Tank Capacity 0.75L
Applicable PCB 50x50-250x330mm	N2 0.4-0.5mps25L/min 99.99%
Palette Size 380Wx300Lmm	Solder Pot Approx. 16kg
Machine Weight Approx. 700Kg	Preheater Carbon Lamp Heater
Power Source Three-phase 200V	Fluxer Two-fluid Nozzle
Air 0.4-0.5mps	



CBSS-5050W "DUAL"

Outer Dimensions 1815Wx1600Lx1600Hmm	Flux Tank Capacity 0.75L
Applicable PCB 50x50-500x500mm	N2 0.4-0.5mps25L/min 99.99%
Machine Weight Approx. 500Kg	Solder Pot Approx. 6.0kg x2set
Power Source Three-phase 200V	Fluxer Two-fluid Nozzle Aero-Jet
Air 0.4-0.5mps	



ULTIMA-NEO-L

Outer Dimensions 1191Wx1761Lx1305Hmm	Flux Tank Capacity 0.75L
Applicable PCB 50x50-380x460mm	N2 0.4-0.5mps25L/min 99.99%
Machine Weight Approx. 500Kg	Solder Pot Approx. 16kg
Power Source Single-phase 200V	Fluxer Two-fluid Nozzle
Air 0.4-0.5mps	

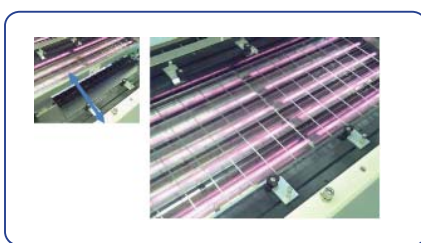
Main specification of machines that supports laege-size PCBs.

	Moving Side	Applicable PCB Size(MAX)	Preheat Options
ULTIMA-SSP-L(Fluxing)"SPROBO-L"	PCB Table	380X460 mm	—
ULTIMA-STR2-L(Soldering), Non-benchtop type	PCB Table	380X460 mm	Sold separately
ULTIMA-NEO-L(Fluxing & Soldering)	PCB Table	380X460 mm	No Option
ULTIMA-MR-M, XL(Fluxing & Soldering)	Fluxer/Solder Pot	300X460 mm 600X600 mm	Retractable Heater
CBSS-5050W(Fluxing & Soldering)	Fluxer/Solder Pot	500X500 mm	Retractable Heater

Benchtop Type Preheater PHS600



Carbon Lamp Heater



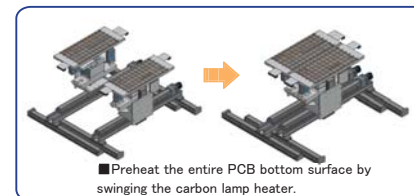
CBSS-5050W/Upper Preheating Mechanism



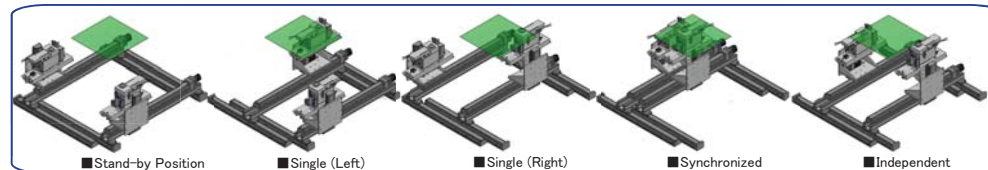
Hot air preheating to the PCB component surface is equipped as a standard specification.



CBSS-5050W/Lower Preheating Mechanism(OP)



CBSS-5050W/Dual Solder Pot Operation



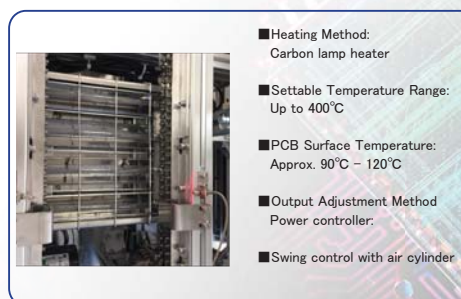
IRD-2533/SCARA Robot



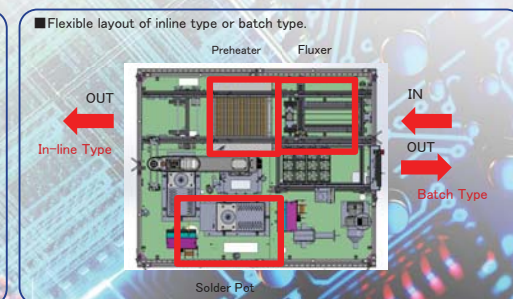
- Turning the PCB and liner operations are possible at the desired angle.
- The flow nozzle can be cleaned automatically.
- Work can be transported with the robot.



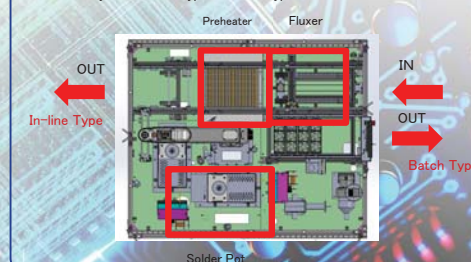
- Equipped with a small automatic spray gun.
- X and Y direction movement with a servo motor
- Two-fluid spray nozzle
- Pressure tank method
- Sub-tank capacity 1.3kg(Max)
- Automatic feeding to sub-tank from 18-square-liter can
- Emitted via Φ197-mm duct on the top side of the machine



- Heating Method: Carbon lamp heater
- Settable Temperature Range: Up to 400°C
- PCB Surface Temperature: Approx. 90°C - 120°C
- Output Adjustment Method: Power controller
- Swing control with air cylinder



Flexible layout of inline type or batch type.



In-line Type Selective Soldering Series



EQS-350SDDD

Outer Dimensions 1400Wx4800Lx1400Hmm	Power Source Three-phase 200V Breaker100mA
Applicable PCB Size 100x100~350x330mm	30kVA
Pass Line 900mm±20mm	Required Duct Exhaust Volume per duct 8m ³ /min
Machine Weight Approx.2,200Kg	Air 0.4~0.5mps N2 25ℓ/min×3

EQSS-350SD+M

Outer Dimensions 1330Wx3550Lx1400Hmm	Power Source Three-phase 200V Breaker100mA
Applicable PCB Size 100x100~330x250mm	22kVA
Pass Line 900mm±20mm	Required Duct Exhaust Volume per duct 10m ³ /min
Machine Weight Approx.1,350Kg	Air 0.4~0.5mps N2 25ℓ/min

SELBO II

Outer Dimensions 1430Wx910Lx1300Hmm ※per module	Power Source Three-phase 200V Breaker100mA
Applicable PCB Size 100x100~350x400mm	Required Duct Exhaust Volume per duct 10m ³ /min Air 0.4~0.5mps N2 25ℓ/min ※per module
Pass Line 900mm±20mm	
Machine Weight Approx.600Kg ※solder pot module	

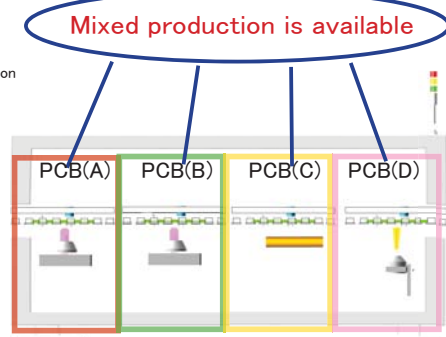
Successful Case of Introducing In-line Type System



Suitable for Small Lot Production with Many Varieties

Mixed production of small lots becomes possible by using (1) barcode management or (2) automatic changeover system and common frame jig for transportation.

All stages operate simultaneously. Set tact balances. To prevent temperature drop, it stops and waits before the preheating zone.



Main Specifications ①

Machine	Spray	Applicable PCB	Preheat Method
EQS-350SDDD (Spray, Preheater, 3 Solder pots)	Two-fluid(Std)/Aero Jet(OP)	350WX330Lmm	Carbon Lamp Heater
EQS-350SDD (Spray, Preheater, 2 Solder pots)	Two-fluid(Std)/Aero Jet(OP)	350WX330Lmm	Carbon Lamp Heater
EQSS-350SD (Spray, Preheater, 1 Solder pot)	Two-fluid(Std)/Aero Jet(OP)	350WX250Lmm	Hot Air
EQSS-350M (Solder pot unit for EQS-350SD)	—	350WX250Lmm	—
SELBO (Module type in-line machine)	Two-fluid/Aero Jet	350WX400Lmm	Carbon Lamp Heater

Main Specifications ②

Solder Pot Zone



Aero Jet Spray (OP)



Preheat Zone

Flux Zone

Carbon Lamp Heater



Hot Air Heater

Two-fluid Spray

Automatic Nozzle Cleaning(OP)



Automatic Solder Feeder(OP)



Fluxer Flowmeter(OP)



Wave Soldering Series



VIS-350

Outer Dimensions
1180Wx1352Lx1222Hmm
Power Source
Three-phase 200V
6 kVA

Applicable PCB
50x100~350x450mm
Required Duct Exhaust Volume per duct
15 m³/min

Pass Line
750mm±20mm

Machine Weight
Approx. 300 kg

WS-302LF

Outer Dimensions
1220Wx3700Lx1460Hmm
Power Source
Three-phase 200V
Breaker 100 mA

Applicable PCB
50x100~300x350mm
Required Exhaust Volume of Conveyor
15m³/min

Pass Line
750mm±20mm

Machine Weight
Approx. 1,350 kg

GFL-350N

Outer Dimensions
1400Wx4853Lx1613Hmm
Power Source
Three-phase 200V
Breaker 100 mA

Applicable PCB
50x120~350x450mm
Required Exhaust Volume of Conveyor
40m³/min

Pass Line
950mm±20mm

Machine Weight
Approx. 1,500kg
Air
0.5mps
30L/min
N2
0.5mps
330L/min

■ Spray Fluxer / VIS-350

■ Opens in 3 forward directions



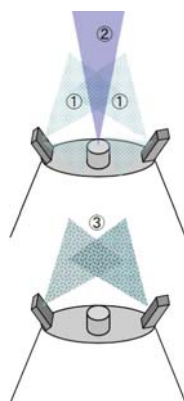
■ Upper dust collection filter with replaceable cassette type



■ Flux tank (level sensor)



■ Air Blowout For Preventing Clogging
Sequence controlled air blow that eliminates flux residue after ejection prevents flux clogging.



■ Lower dust collection filter



■ Finger cleaning brush



■ Filter slide-out



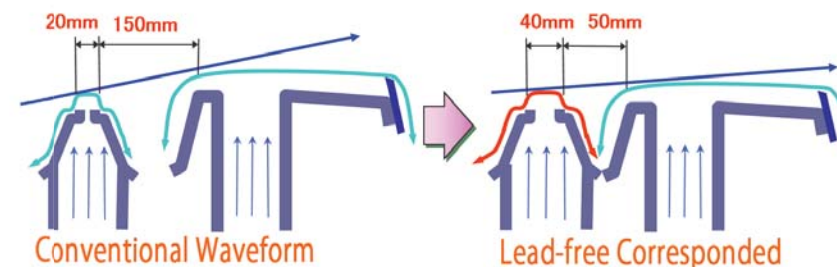
■ Spray Efficiency

Before (g)	After (g)	Adhered (g)	Sprayed (g)	Efficiency (%)
239.97	240.31	+0.39	+0.47	82.9
239.97	240.31	+0.39	+0.46	84.7

※Conducted two times

※Adhered amount is a measured value of solid content after natural drying (more than 10 min.)
Sprayed amount is also calculated based on the measured solid content.

■ Inclined Type Air Flow Soldering System/WS-302LF



■ The width of the first wave has been increased to secure DIP time for lead-free solder with low wettability.

■ Narrowed the interval of the first and second wave nozzles from 150mm to 50mm so that the temperature drop can be reduced. (Supports the second wave temperature recovery)

■ By increasing the solder flow pressure, the solder contactability to PCB and the quality of through-hole up have improved.

■ The peel back point of the second wave can be set with the external handle. Solder fillet formation / Reducing solder bridge



■ Wing plate handle

■ Check gauge

■ Rear damper handle

■ Inclined Type N2 Flow Soldering System/GFL-350N



■ N2 tunnel structure without blocking curtains



■ Removal tunnel cover

■ Open tunnel structure without air block curtain /supports component

heights up to 100mm. ■ Inlet & outlet pressure control systems to maintain

low O2 level inside the tunnel. ■ Wave soldering system designed to reduce

solder dross & solder ball generation. ■ Dipping-zone PCB warp prevention

unit operable externally without need to open the tunnel (Option)

■ Externally-operable peel-back point adjustment unit at dipping zone (Option)

■ Dross generation state in the air flow



■ Dross amount after introducing of GFL350N



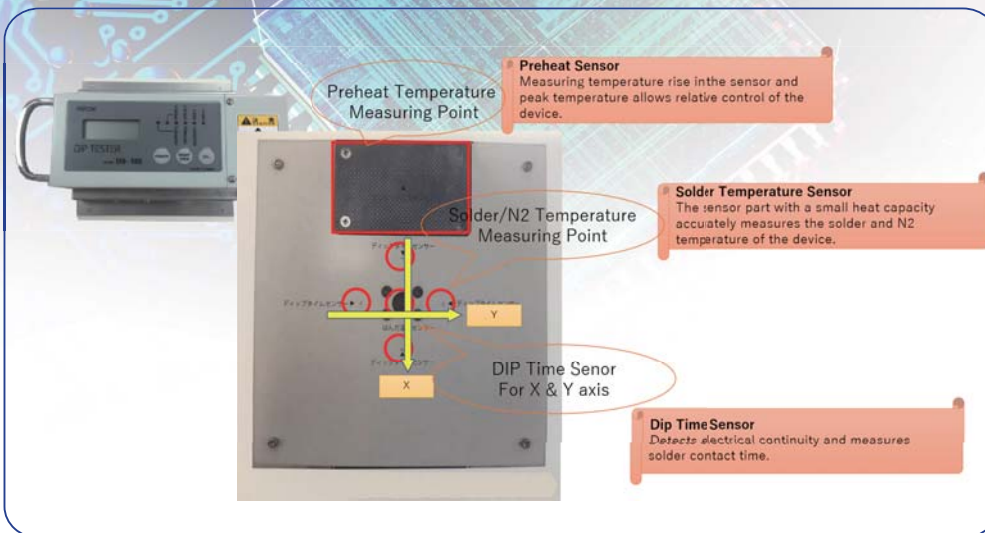
With air flow soldering, the average daily consumption is 5 to 8 solder bars.
(Cost range approx. ¥20,000 - ¥30,000)

8-hour operation

700g/day



■ Dip Tester For Selective Soldering System DS-10S (Malcom)



■ DS-10S/Measurement Data Specifications / General Specifications

Items	Sensor	Memory	Display	Meas. Range	Accuracy
Solder temperature	K-type sheath thermocouple	5	Digital LCD 3-digit and PC Software	0 - 330°C	±1°C
PCB lower surface temperature	K-type thermocouple	5		0 - 330°C	±1°C
Dip time	Electrode (8 pcs.)	5		0 - 10.0 sec	±0.2 sec
X, Y axis moving speed	Electrode (8 pcs.)	5		0 - 20mm/sec	—
X, Y solder size	Electrode (8 pcs.) Calculated from the moving speed & contact time to the electrodes.	5	PC Software	0 - 35mm	—
Temp. profile (sampling: 50ms)	Solder/Preheat sensor	1		0 - 330°C	±1°C

Items	Remark
Cold contact point compensation	Automatic compensation with platinum temp. measuring resistor.
Ambient temperature	150°C and within 5 minutes
Power supply	AAA battery x 2 pcs.
External connection	USB(mini B type)
Number of memory	1 data /5 connection (nozzle stages) available
Sampling time	50 ms (fixed)
Outer dimensions	214mm(D) × 78mm(W) × 43.6mm(H)
Weight	820g (without batteries)

■ Small Type Nitrogen Gas Generator (KOFLOC)

Nitrogen gas generating volume **increased by up to 54.5%**, achieving industry No.1 performance.*1

Sound level of 58.8dB achieved in front of device.*2

New LCD panel used.

Note*1&*2
Based on public information
announced by KOFLOC.



■ What is a nitrogen gas generator?

The nitrogen gas generator is designed to supply nitrogen gas by extracting nitrogen from air.



Nitrogen Gas Generator Mounted Table



Specifications			
Purity(%)	99.99	Dew Point	≤ -55°C
Generating Volume (NL/min)	30.0	Dimension	1300 × 780 × 520
Pressure(MPa)	0.4	Weight	Approx.205kg
Electricity Consumption	100w	PW Voltage	AC100V 50/60Hz
Air Condition	200~250L/min 0.5~0.65MPa ≤ 10°C Oil free and dry air		

Option List

■For selective soldering system

	TRZ	STR2-L	SSP	SSP-L	IRD-2533	CBSS	NEO-L	EQS-350	SELBO II
Applicable PCB Size (Max)	250x330mm	380x460mm	250x330mm	380x460mm	250x330mm	500x500mm	380x460mm	350x330mm	350x400mm
Superfine Nozzle (φ 2、φ 2.5、φ 3、φ 4mm)	○	○	—	—	○	○	○	○	○
Standard Nozzle (10 sizes from φ 5 to φ 20mm)	○	○	—	—	○	○	○	○	○
Safety Cover (Front/Upper area sensor/Exhaust duct)	○	○	—	—	—	—	○	—	—
Safety Cover (No area sensor/Exhaust duct)	○	○	—	—	—	—	○	—	—
Safety Cover (for SSP/ open&close type)	○	—	○	○	—	—	—	—	—
Safety Cover (for SSP/area sensor type)	—	—	○	○	—	—	—	—	—
Input with Scanner & Gerber data NC creation software	○	○	—	—	Standard Equipment	Standard Equipment	Standard Equipment	Standard Equipment	Standard Equipment
Weekly Timer	○	○	—	—	○	○	○	○	○
Solder Low-level Warning System	○	○	—	—	○	○	○	○	○
Three-light Signal Tower	○	○	○	○	○	○	○	○	○
Laser-type Wave Height Detection & Feedback Control	○	○	—	—	○	○	○	○	○
CCD Camera Teaching & Camera Simulation	○	○	—	—	—	○	○	—	—
Automatic Solder Feeder (φ 2mm/1-kg bobbin)	○	○	—	—	○	○	○	○	○
Witness Camera (USB connection/ wih LED light)	○	○	—	—	○	○	○	○	○
Bar/QR-code-enabled Automatic PCB Model Switching	○	○	○	○	○	○	○	○	○
Automatic Nozzle Cleaning System	×	×	—	—	○	○	×	○	○
Adoptive Voltage/Step-down Transformer	○	○	—	—	○	○	○	○	○
Specifying Color	○	○	○	○	○	○	○	○	○
Spare Solder Pot	○	○	—	—	○	○	○	○	○
Automatic Width Adjustment	—	—	—	—	—	—	○	○	○
Preheating Process	Separate Unit	Separate Unit	—	—	Standard Equipment	Up&Low(OP)	No Option	Standard Equipment	Standard Equipment
PCB Detection & Error Proofing System	—	—	○	○	—	○	○	—	—
Flux Flowmeter	—	—	○	○	○	○	○	○	○

Safety Cover for TRZ



Safety Cover for SSP



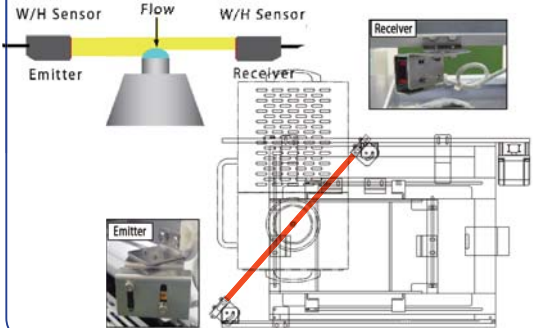
PCB Detection & Error Proofing Sensor



Scanning System with CCD Camera



Wave Height Detection



■ Automatic Nozzle Cleaning

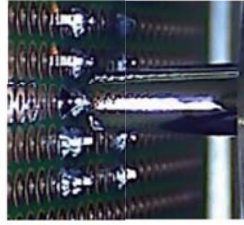
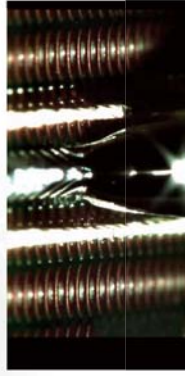
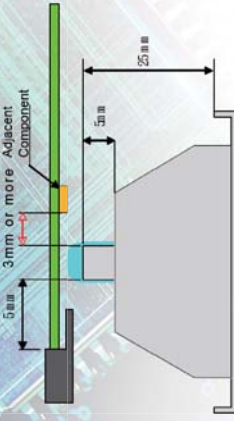
■ Automatic Solder Feeder

■ Flux Flowmeter

⇒ See page 8

■ Superfine Nozzle/ Φ2.0 2.5 3.0 4.0 mm

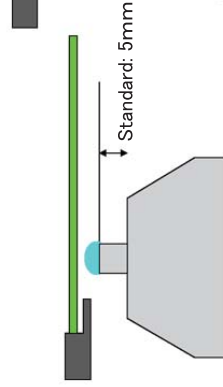
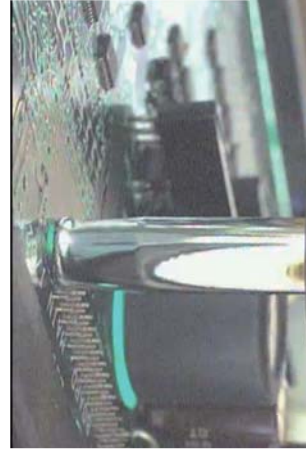
Superfine Nozzle
Actual value: 1mm
3mm or more
Adjacent
Component



Lead Pitch: 2.5 mm, Land Interval: 0.5 mm
Solderable only in the middle.



■ Long Nozzle



Available up to 35mm(OP)

■ N2 Temperature



without N2 Heating

Settings

N2 Heater Set Temp: 350°C

N2 Volume: 200/min

Solder Pot Set Temp: 280°C

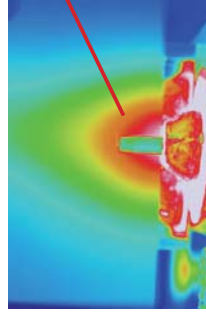
Benefits of using N2 heating

Preheating PCBs

Flux activation (Wettability improvement)

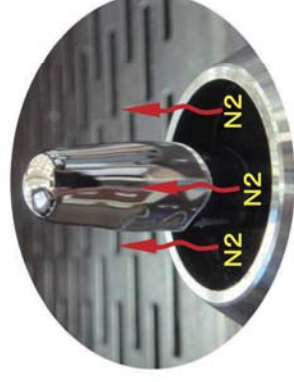
Bridge reduction by low oxygen atmosphere

Nozzle oxidation prevention (Stable flow)

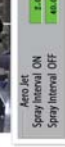


Approx. 200°C

With N2 Heating



■ Fluxer/Aero Jet Nozzle



Step	Step	Mode	Speed (mm/s)	Time (sec)	Volume (mm³)	Height (mm)	Width (mm)
1	Preheat	ON	1.0	10.0	10.0	10.0	10.0
2	Preheat	ON	1.0	10.0	10.0	10.0	10.0
3	Preheat	ON	1.0	10.0	10.0	10.0	10.0
4	Preheat	ON	1.0	10.0	10.0	10.0	10.0
5	Preheat	ON	1.0	10.0	10.0	10.0	10.0
6	Preheat	ON	1.0	10.0	10.0	10.0	10.0
7	Preheat	ON	1.0	10.0	10.0	10.0	10.0
8	Preheat	ON	1.0	10.0	10.0	10.0	10.0
9	Preheat	ON	1.0	10.0	10.0	10.0	10.0
10	Preheat	ON	1.0	10.0	10.0	10.0	10.0

Point Mode

Short Long (sec)

Liner Mode

Slow Fast (mm/s)

Point Mode

Short Long (sec)

Liner Mode

Slow Fast (mm/s)

Point Mode

Short Long (sec)

Liner Mode

Slow Fast (mm/s)

Point Mode

Short Long (sec)

Liner Mode

Slow Fast (mm/s)

Point Mode

Short Long (sec)

Liner Mode

Slow Fast (mm/s)

Point Mode

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Short Long (sec)

Liner Mode

Slow Fast (mm/s)

Point Mode

Short Long (sec)

Liner Mode

Slow Fast (mm/s)

Point Mode

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Company Information

■ Overview

Company Name: KOKI TEC CORP. Head Office: 2-8-40 Yoshinodai, Kawagoe-City, Saitama 350-0833 Japan
 Tel:+81-49-229-5280 Fax:+81-49-229-5310
Establishment Date: November 6, 1985
Capital: 80 Million Yen
President: Eiji Mori
Financing Banks: Saitama Resona Bank, Limited. Urawa-Chuo BO
 MUFG Bank, Ltd. Ginzadori BO
 Mizuho Bank, Ltd. Omiya BO
 Sumitomo Mitsui Banking Corporation Shinbashi BO
Type of Business: Manufacturing and sales of automatic soldering system such as flow machines, reflow machines and spray fluxes.
Number of Employees: 45
Nagoya Branch: #102 II, 7-4-28, Kozoji-cho, Kasugai-city, Aichi 487-0013 Japan
 Tel:+81-568-29-7075 Fax:+568-29-7076
Osaka Branch: #301, 1-2-6, Minoh, Minoh-city, Osaka 562-0001 Japan



■ Overseas Sales bases & Maintenance bases

China	KOKI TEC (SHENZHEN) CO., LTD Room A, 4th Floor Laifu Building, Left Side of 2 Fuyong Subdistrict Office Baoan District, Shenzhen City Guangdong Province, P.R.C Tel: +86-755-2738-0950 Fax: +86-755-2733-2202	Thailand	TREND Electronics (Thailand) Co., Ltd. www.trend.co.th
Korea	KOKI TEC KOREA http://www.kokitec.co.kr	Malaysia	TREND ELECTRONICS (M) SDN.BHD. www.trend.com.my
Taiwan	Wave Jet Electrical Co., Ltd. www.wavejet.com.tw	Vietnam	MEDIN CO., LTD. www.medin.com.vn
		Mexico	SUN-WA TECHNOS MEXICO S.A. DE C.V. www.sunwa.co.jp
		India	SUMITRON EXPORTS PVT. LTD. www.sumitron.com
		Brazil	MEGURO INSTRUMENTOS ELECTRONICOS LTDA. www.meguro.com.br